

主要材料/BOM 清单信息(Information of Material/BOM list):

样品验证，禁止量产！

| 材料 |             |                                      | 描述                                 | 备注   |
|----|-------------|--------------------------------------|------------------------------------|------|
| 1  | 基板          | S57731JM2M                           | 240X76. 3X0. 30                    | 客供   |
| 2  | A芯<br>U1    | WUM577SD1M-V0                        | 971. 9*1001. 6*200um<br>(不含bump高度) | 客供   |
| 3  | B芯<br>U2/U3 | WSD377PB1M                           | 395*530*200um<br>(不含bump高度)        | 客供   |
| 4  | C芯<br>U4    | WLN577GD2M-31M                       | 892*1212*200um<br>(不含bump高度)       | 客供   |
| 5  | D芯<br>U5    | WSI577CD1M-C0                        | 794*1374*200um<br>(不含bump高度)       | 客供   |
| 6  | E芯<br>U6    | WUM577SD3M-001MC1                    | 921. 4*1166. 2*200um<br>(不含bump高度) | 客供   |
| 7  | F芯<br>U7    | WSD577PB1M                           | 410*560*200um<br>(不含bump高度)        | 客供   |
| 8  | 助焊剂         | TACFlux026S                          | /                                  | 钢泰   |
| 9  | 塑封料         | EME-G311Q Type L<br>ver. GR          | /                                  | 住友电木 |
| 10 | 焊膏          | TF247-M305NI-F-860                   | /                                  | 同方   |
|    |             | PasteF590<br>Sn99. 3Cu0. 7-89M4 (LH) |                                    | 贺利氏  |
| 11 | 分离膜         | TB 50 μ m*142mm TOWA                 | /                                  | TOWA |

|         |        |
|---------|--------|
| 模具      | C模     |
| 基板切割道宽度 | 0. 2mm |

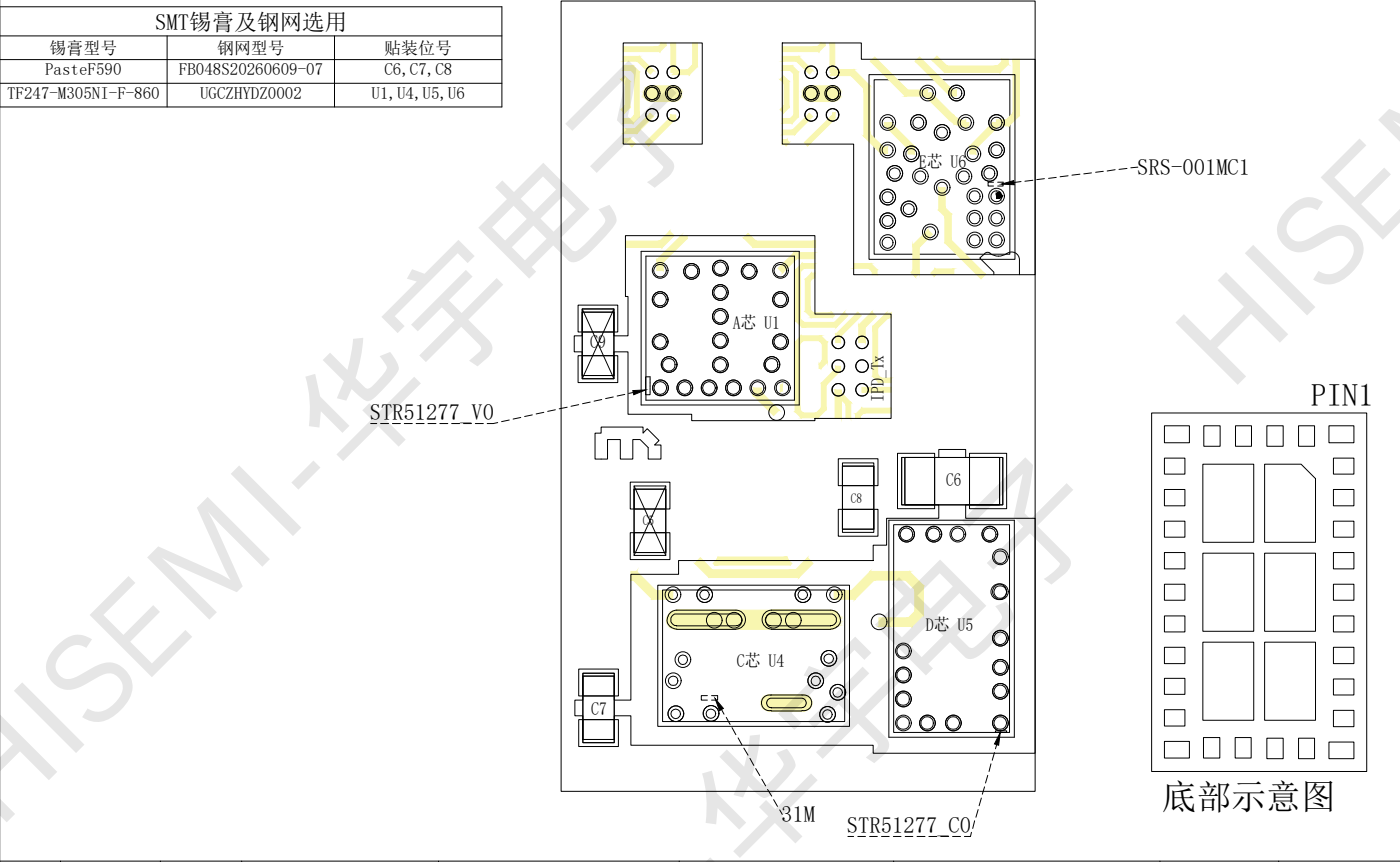
|                   |                                     |          |                        |                                  |  |
|-------------------|-------------------------------------|----------|------------------------|----------------------------------|--|
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| 研发审核<br>R&d check | 产品工程审核<br>Product engineering check |          | 批准<br>Approved by      |                                  |  |

\*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！  
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站别SMT

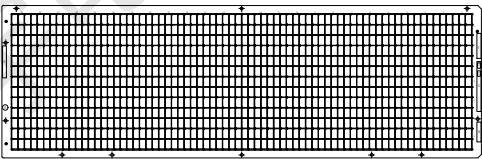
PIN1

样品验证，禁止量产！



| NO.      | Item | tags | Reference          | value                                 | package                                | Description          | KD P/N | Quantity |   |
|----------|------|------|--------------------|---------------------------------------|----------------------------------------|----------------------|--------|----------|---|
| 1        | 电容   | C6   | GRM033R60J224ME15D | 220nF±20% 6.3V                        | 0201                                   | /                    |        | 1        |   |
| 2        | 电容   | C7   | GRM022R61A104ME01L | 0.10 μ F±20% 10V                      | 01005                                  | /                    |        | 1        |   |
| 3        | 电容   | C8   | GJM0225C1ER40WB01D | 0.4pF±0.05pF                          | 01005                                  | /                    |        | 1        |   |
| 4        | A芯   | U1   | WUM577SD1M-V0      | STR51277_V0<br>68um (35Cu+3Ni+30SnAg) | 971.9*1001.6(μm²)<br>38.26*39.43(mil²) | 200um<br>(不包含bump高度) |        | 1        |   |
| 5        | C芯   | U4   | WLN577GD2M-31M     | 31M<br>70um (40Cu+30SnAg)             | 892*1212(μm²)<br>35.12*47.72(mil²)     | 200um<br>(不包含bump高度) |        | 1        |   |
| 6        | D芯   | U5   | WSI577CD1M-C0      | STR51277_C0<br>68um (35Cu+3Ni+30SnAg) | 794*1374(μm²)<br>31.26*54.09(mil²)     | 200um<br>(不包含bump高度) |        | 1        |   |
| 7        | E芯   | U6   | WUM577SD3M-001MC1  | SRS-001MC1<br>68um (35Cu+3Ni+30SnAg)  | 921.4*1166.2(μm²)<br>36.28*45.91(mil²) | 200um<br>(不包含bump高度) |        | 1        |   |
| 8        | 基板   | /    | S57731JM2M         | 基板                                    | /                                      | /                    |        | 1        |   |
| 9        | 锡膏   | /    | /                  | TF247-M305NI-F-860                    | /                                      | 仅U1、U4、U5、U6使用       |        | /        |   |
|          |      |      |                    | PasteF590<br>Sn99.3Cu0.7-89M4 (LH)    |                                        | 其他元器件使用              |        |          |   |
| SMT元器件总计 |      |      |                    |                                       |                                        |                      |        |          | 7 |

框架传送方向（装片）：  
L/F Direction (D/A)：上侧三个圆孔



实物图：  
Chip photo:

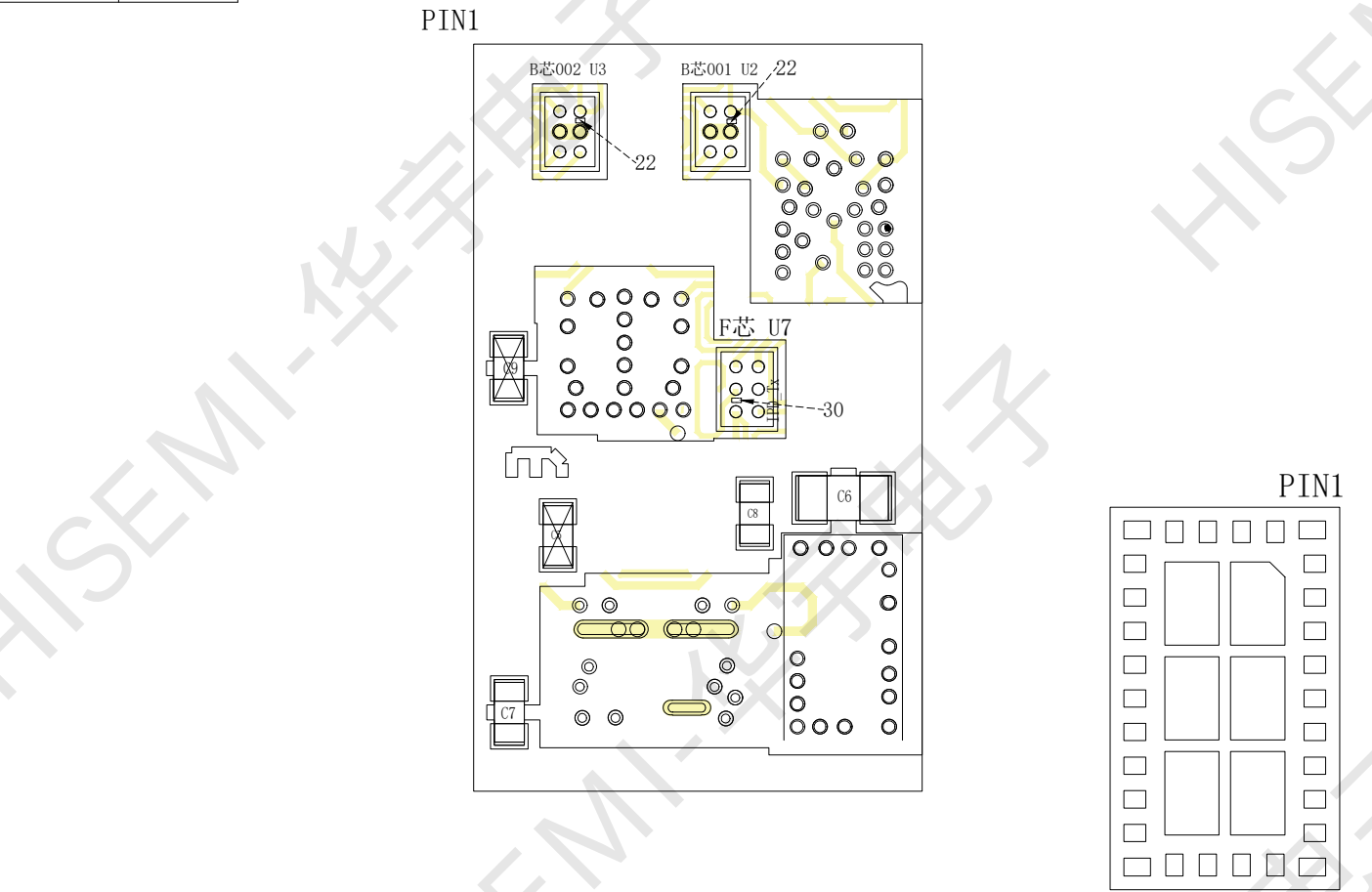


特殊说明 Special Instructions：

SMT注意：  
1.控制溢锡，防止沾锡。

|                                                                                                                                                                                                                      |  |   |  |                      |  |                  |  |                    |  |                  |  |                                                     |  |                  |  |                       |  |
|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--|---|--|----------------------|--|------------------|--|--------------------|--|------------------|--|-----------------------------------------------------|--|------------------|--|-----------------------|--|
| <div><div><div><div></div><div></div></div><div><div></div><div></div></div></div><div><div>池州华宇电子科技股份有限公司</div><div>CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD</div><div>焊线图纸 Bonding Diagram</div></div></div> |  |   |  | 客户代码<br>Customer No. |  | 1200             |  | 线图号<br>Drawing No. |  | HY-PX-1200-148 A |  |                                                     |  | 页码 Page<br>3 / 6 |  |                       |  |
|                                                                                                                                                                                                                      |  |   |  | 产品名称<br>Product Type |  | STR51277-31 M1.0 |  |                    |  | 封装外型<br>PKG Type |  | FCLGA36L(3.0X5.0X0.74-P0.44)                        |  |                  |  |                       |  |
| 助焊剂<br>Flux                                                                                                                                                                                                          |  | / |  | /                    |  | /                |  | /                  |  | /                |  | 塑封料型号(绿色环保)<br>Compound Type (Green)                |  |                  |  | 基板编码<br>Substrate No. |  |
| TACFlux026S                                                                                                                                                                                                          |  | / |  | /                    |  | /                |  | /                  |  | /                |  | 首选(Preferred): G311Q Type L ver.GR<br>备选(Optional): |  |                  |  | S57731JM2M            |  |
| 客户图号<br>Customer drawing NO.                                                                                                                                                                                         |  |   |  |                      |  |                  |  |                    |  |                  |  |                                                     |  |                  |  |                       |  |

|    |    |            |  |  |  |  |  |  |  |
|----|----|------------|--|--|--|--|--|--|--|
| 站别 | FC | 样品验证，禁止量产！ |  |  |  |  |  |  |  |
|----|----|------------|--|--|--|--|--|--|--|



注意：  
1.B芯和F芯芯片名称一致，请注意bump面logo； B芯和F芯按Map 取die。

|                                     |  |  |  |                     |  |  |  |                            |  |  |  |
|-------------------------------------|--|--|--|---------------------|--|--|--|----------------------------|--|--|--|
| 框架传送方向（装片）：<br>L/F Direction (D/A)： |  |  |  | 实物图：<br>Chip photo： |  |  |  | 特殊说明 Special Instructions： |  |  |  |
|                                     |  |  |  |                     |  |  |  |                            |  |  |  |

| 序号                | 芯片名称       | Die ID | 芯片尺寸<br>(with scribe line)        | 划片道宽度                               | 晶圆尺寸 | 圆片工艺 | 芯片厚度UM                | 来料方式     | Wafer material* | Bump type*             | Bump composition*         | Min bump pitch<br>(space + bump size)*<br>UM | Min bump height*<br>UM | Min bump diameter*<br>UM |
|-------------------|------------|--------|-----------------------------------|-------------------------------------|------|------|-----------------------|----------|-----------------|------------------------|---------------------------|----------------------------------------------|------------------------|--------------------------|
| B芯<br>U2/U3       | WSD377PB1M | 22     | 395*530(μm²)<br>15.55*20.87(mil²) | 60um                                | 8寸   | 3um  | 200um<br>(不包含 bump高度) | 晶圆 wafer | SI (RX Filter)  | Pillar bump            | 93um<br>(55Cu+3Ni+35SnAg) | 135                                          | 93                     | 80                       |
| F芯<br>U7          | WSD577PB1M | 30     | 410*560(μm²)<br>16.14*22.05(mil²) | 60um                                | 8寸   | 3um  | 200um<br>(不包含 bump高度) | 晶圆 wafer | SI              | Pillar bump            | 93um<br>(55Cu+3Ni+35SnAg) | 150                                          | 93                     | 80                       |
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| 研发审核<br>R&d check |            |        |                                   | 产品工程审核<br>Product engineering check |      |      | 批准<br>Approved by     |          |                 |                        |                           |                                              |                        |                          |

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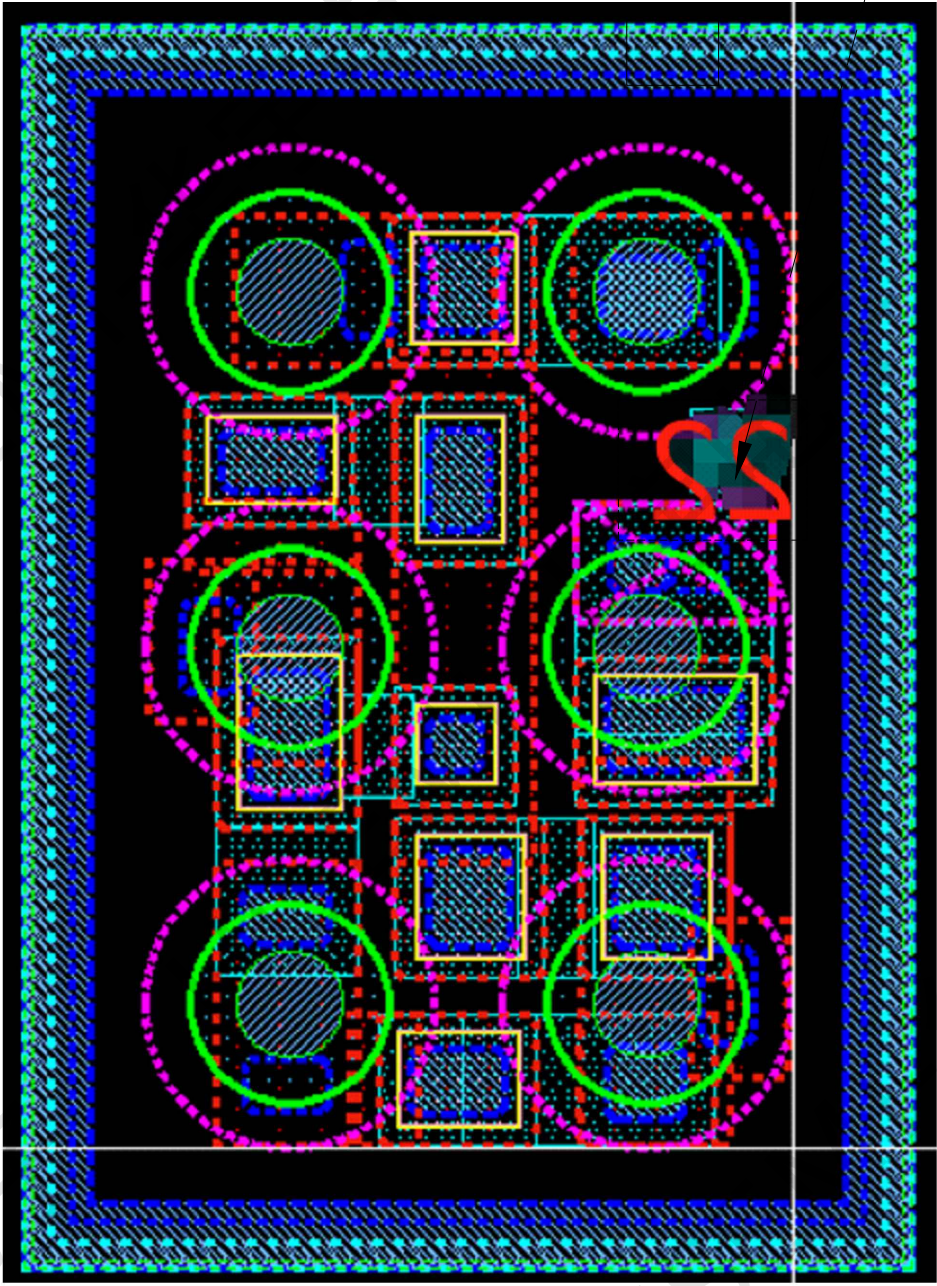
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|                                                                                                                                                                                         | 产品名称<br>Product Type | STR51277-31 M1.0 |                    | 封装外型<br>PKG Type | FCLGA36L(3.0X5.0X0.74-P0.44) |                  |

U2/U3取片图 (TOP VIEW):

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/按目标区域取DIE:

/ ID: 22

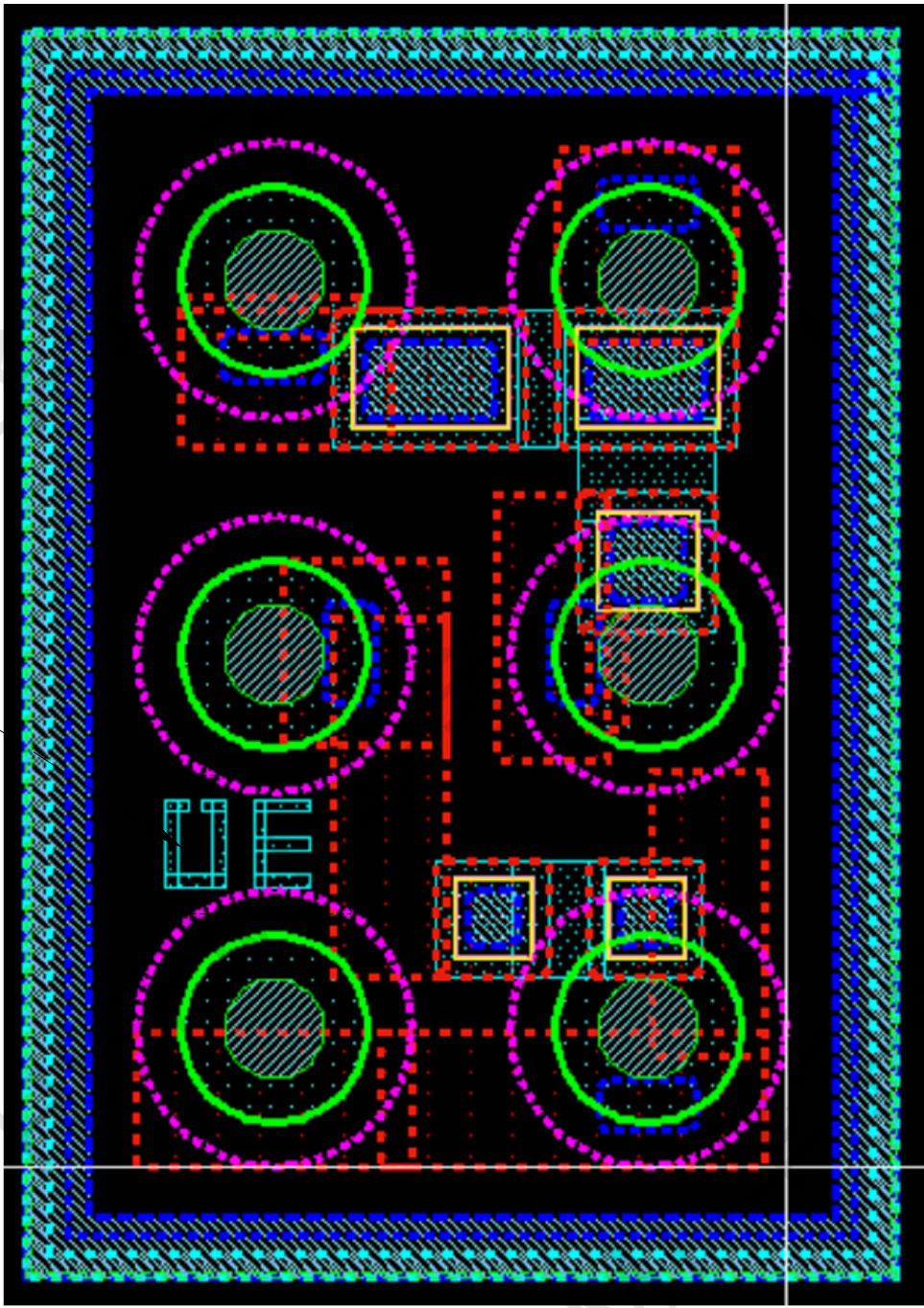


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U7取片图 (TOP VIEW):

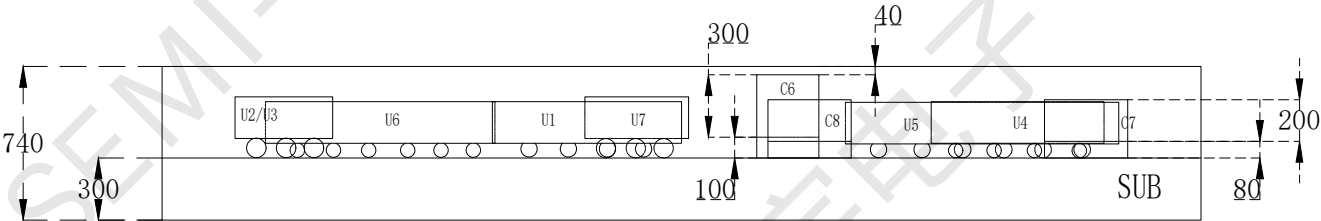
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按目标区域取DIE:  
ID: 30



|                                                                                                                                                                                       |                      |                  |                    |                  |                              |                  |
|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------|------------------|--------------------|------------------|------------------------------|------------------|
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|                                                                                                                                                                                       | 产品名称<br>Product Type | STR51277-31 M1.0 |                    | 封装外型<br>PKG Type | FCLGA36L(3.0X5.0X0.74-P0.44) |                  |

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|                                                                                                                                                                                                                                                                                                                                               |                                     |          |                        |                                  |
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